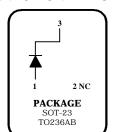


MMBD301

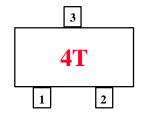
DISCRETE POWER AND SIGNAL TECHNOLOGIES

CONNECTION DIAGRAM



PACKAGE

SOT-23 TO-236AB (Low)



Schottky Barrier Diode

Sourced from Process GD

Absolute Maximum Ratings* TA = 25°C unless otherwise noted

| Sym | Parameter | Value | Units |
|------------------|---|-------------|--------------------|
| T _{sta} | Storage Temperature | -55 to +150 | οС |
| T _J | Operating Junction Temperature | -55 to +125 | οС |
| W _{iv} | Working Inverse Voltage | 25 | V |
| P _F | Forward Power Dissipation @ T _A = 25°C | 200 | mW |
| | Derate above 25 ^o C | 2.0 | Mw/ ^o C |

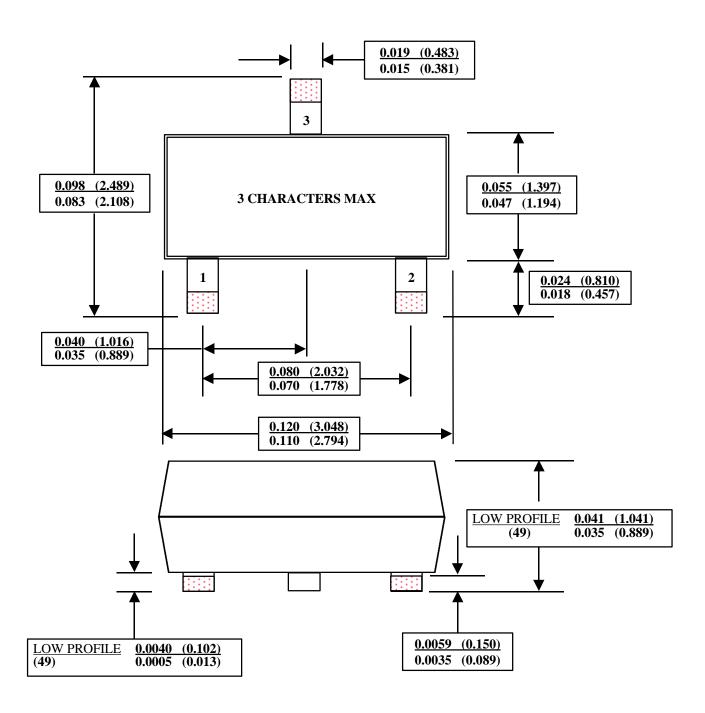
^{*}These ratings are limiting values above which the serviceability of any semiconductor device may be impaired

Electrical Characteristics TA = 25°C unless otherwise noted

| SYM | CHARACTERISTICS | MIN | MAX | UNITS | TEST CONDITIONS |
|--------------------------------|-----------------|-----|------------|-------------------------------|---|
| B _V Bre | akdown Voltage | 30 | | V | $I_R = 10 \text{ uA}$ |
| I _R Rev | verse Leakage | | 200 | nA | V _R = 25 V |
| V _F For | ward Voltage | | 450 600 | mV mV | $I_F = 1.0 \text{ mA}$ $I_F = 10 \text{ mA}$ |
| C _⊤ Ca _l | | 1.5 | pF | $V_{R} = 15 V$ f = 1.0 MHz | |

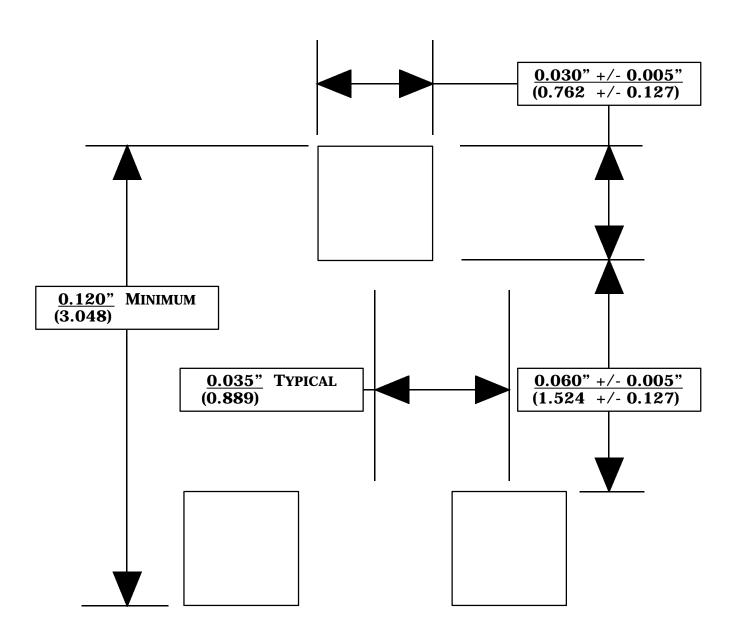
© 1997 Fairchild Semiconductor Corporation





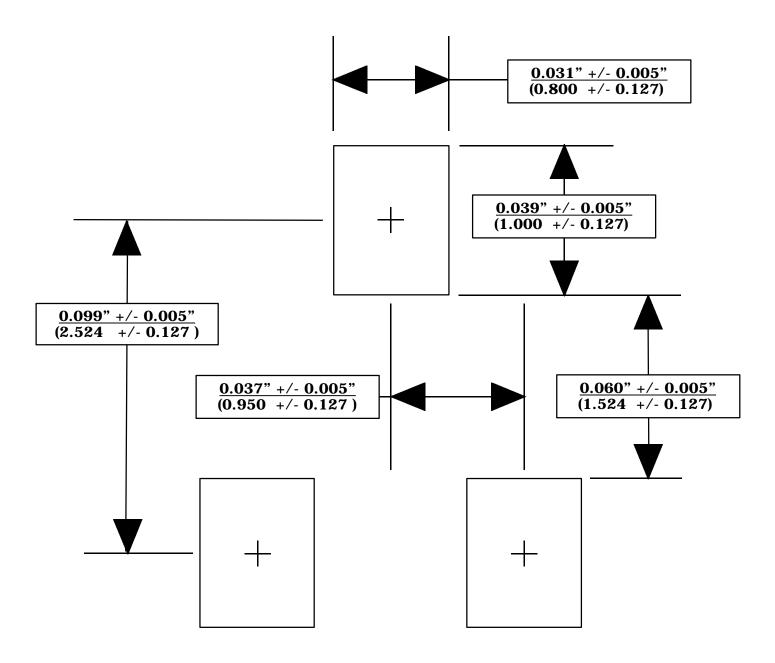
SOT-23
TO-236AB (LOW PROFILE)
22-August-1994



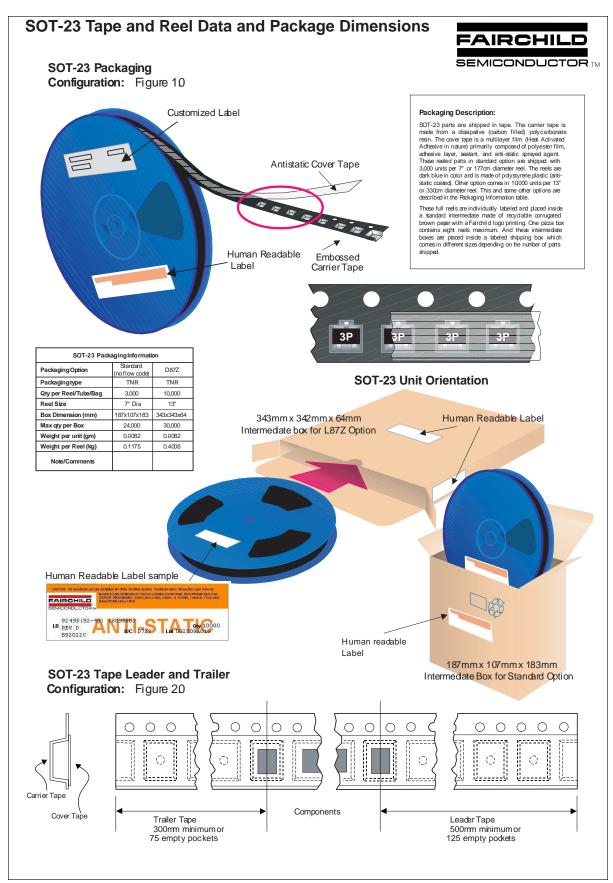


RECOMMENDED SOLDER PADS FOR SOT-23





RECOMMENDED SOLDER PADS
FOR
U.S. & European SOT-23
&
Japanese SC-59

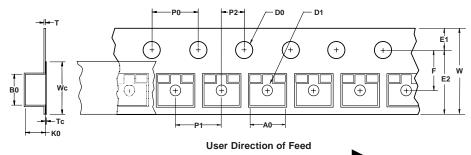


September 1999, Rev. C

SOT-23 Tape and Reel Data and Package Dimensions, continued

SOT-23 Embossed Carrier Tape

Configuration: Figure 3.0



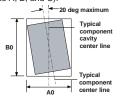
| Dimensions are in millimeter | | | | | | | | | | | | | | |
|------------------------------|-----------------|-----------------|---------------|-----------------|-------------------|-----------------|-------------|-----------------|---------------|---------------|-----------------|-------------------|---------------|-----------------|
| Pkg type | Α0 | В0 | w | D0 | D1 | E1 | E2 | F | P1 | P0 | K0 | Т | Wc | Тс |
| SOT-23 (8mm) | 3.15 +/-0.10 | 2.77 +/-0.10 | 8.0 +/-0.3 | 1.55 +/-0.05 | 1.125 +/-0.125 | 1.75 +/-0.10 | 6.25 min | 3.50 +/-0.05 | 4.0 +/-0.1 | 4.0 +/-0.1 | 1.30 +/-0.10 | 0.228 +/-0.013 | 5.2 +/-0.3 | 0.06 +/-0.02 |

Notes: A0, B0, and K0 dimensions are determined with respect to the EIA/Jedec RS-481 rotational and lateral movement requirements (see sketches A, B, and C).



Sketch A (Side or Front Sectional View)

Component Rotation



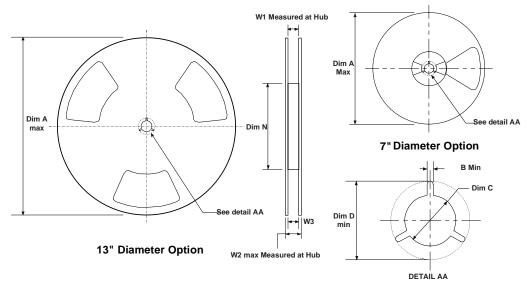
Sketch B (Top View)
Component Rotation



Sketch C (Top View)

Component lateral movement

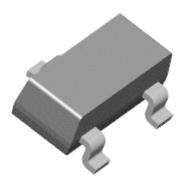
SOT-23 Reel Configuration: Figure 4.0

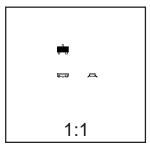


| Dimensions are in inches and millimeters | | | | | | | | | |
|--|----------------|---------------|--------------|-----------------------------------|---------------|-------------|-----------------------------------|---------------|-----------------------------|
| Tape Size | Reel Option | Dim A | Dim B | Dim C | Dim D | Dim N | Dim W1 | Dim W2 | Dim W3 (LSL-USL) |
| 8mm | 7" Dia | 7.00 177.8 | 0.059 1.5 | 512 +0.020/-0.008 13 +0.5/-0.2 | 0.795 20.2 | 2.165 55 | 0.331 +0.059/-0.000 8.4 +1.5/0 | 0.567 14.4 | 0.311 - 0.429 7.9 - 10.9 |
| 8mm | 13" Dia | 13.00 330 | 0.059 1.5 | 512 +0.020/-0.008 13 +0.5/-0.2 | 0.795 20.2 | 4.00 100 | 0.331 +0.059/-0.000 8.4 +1.5/0 | 0.567 14.4 | 0.311 - 0.429 7.9 - 10.9 |

SOT-23 Tape and Reel Data and Package Dimensions, continued

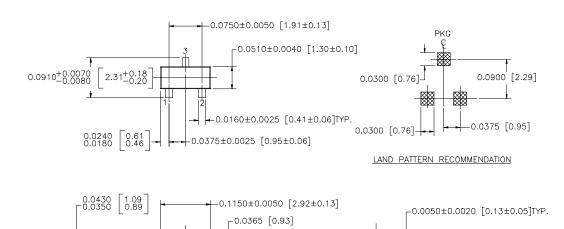
SOT-23 (FS PKG Code 49)





Scale 1:1 on letter size paper Dimensions shown below are in: inches [millimeters]

Part Weight per unit (gram): 0.0082



CONTROLLING DIMENSION IS INCH VALUES IN [] ARE MILLIMETERS SOT 23, 3 LEADS LOW PROFILE

NOTE: UNLESS OTHERWISE SPECIFIED

0.0040 0.10 TYP.

- 1. STANDARD LEAD FINISH 150 MICROINCHES / 3.81 MICROMETERS MINIMUM TIN / LEAD (SOLDER) ON ALLOY 42
- 2. REFERENCE JEDEC REGISTRATION TO-236, VARIATION AB, ISSUE G, DATED JUL 1993

September 1998, Rev. A1

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|--------------------------|---------------------------|---|--|--|--|--|
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| No Identification Needed | Full Production | This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design. | | | | |
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Rev. [